



SCIENTECH

Sciencetech Corp(3583:TT)

M.T. Hsu 2024/06/27

Safe Harbor Statement



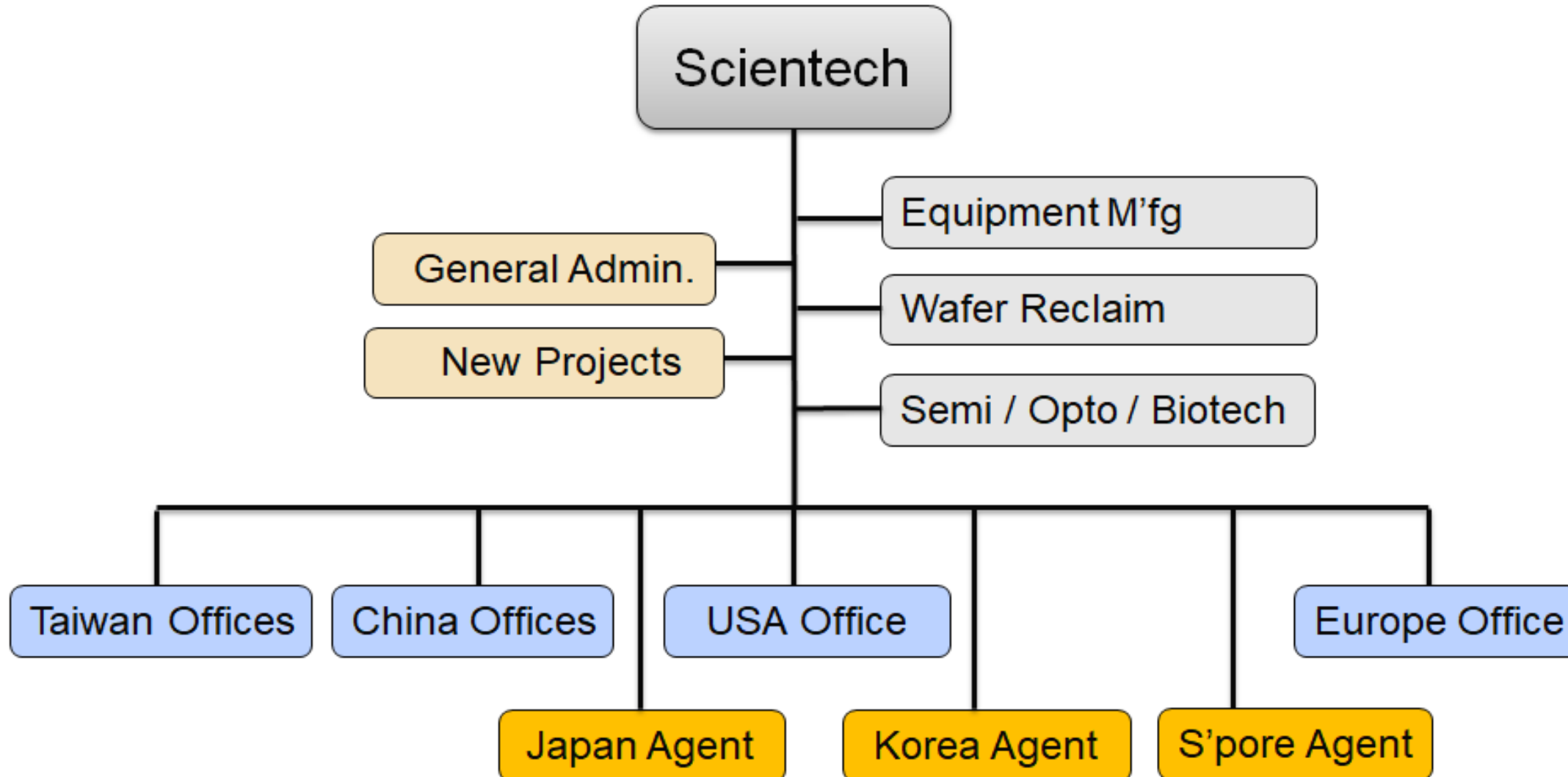
- **This Presentation contains certain forward-looking statements that are based on current expectations and are subject to known and unknown risks and uncertainties that could cause actual results to differ materially from those expressed or implied by such statements.**
- **Except as required by law, we undertake no obligation to update any forward –looking statements, whether as a result of new information, future events or otherwise.**

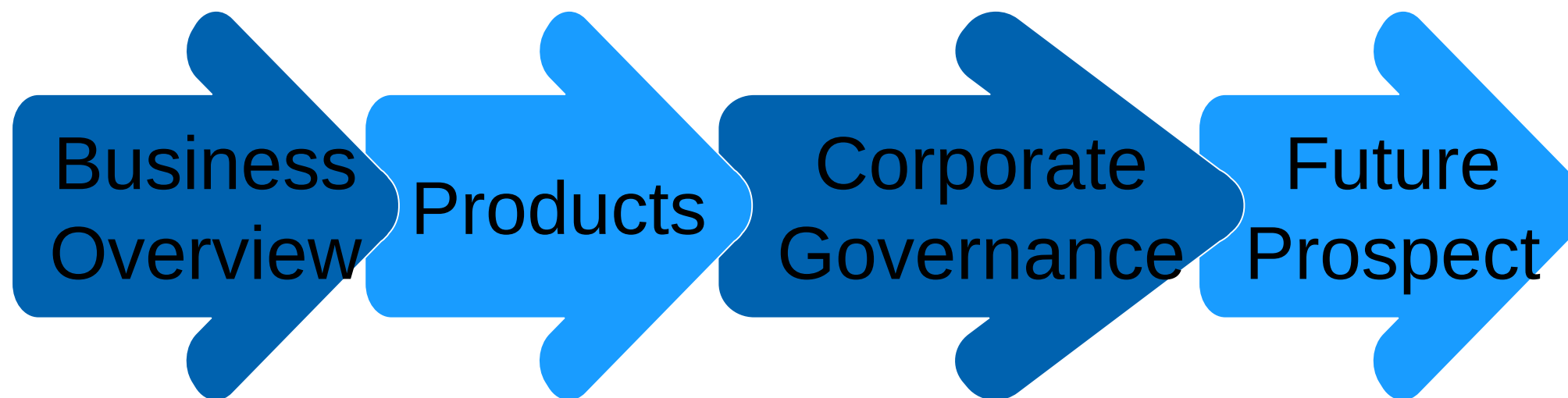
Sciencetech Corp (3583:TT)



Establishment	1979/10/17
Chairman	H.L. Hsieh
CEO	M.T. Hsu
Capital	NT\$ 803 Million
Revenue(2023)	NT\$ 6,911 Million (Consolidated)
No. Employees	875 (Consolidated)
Location	Taiwan : Taipei, Hukou , Hsinchu, Tainan, Kaohsiung Subsidiary Company : China(17 cities including Shanghai) , HK,USA , Europe(Austria) Business Support : Japan,Singapore,South Korea
Products	Equipment Manufacturing 、 Wafer Reclaim 、 Trading(Agent/Distributor)

Organization





Business Overview



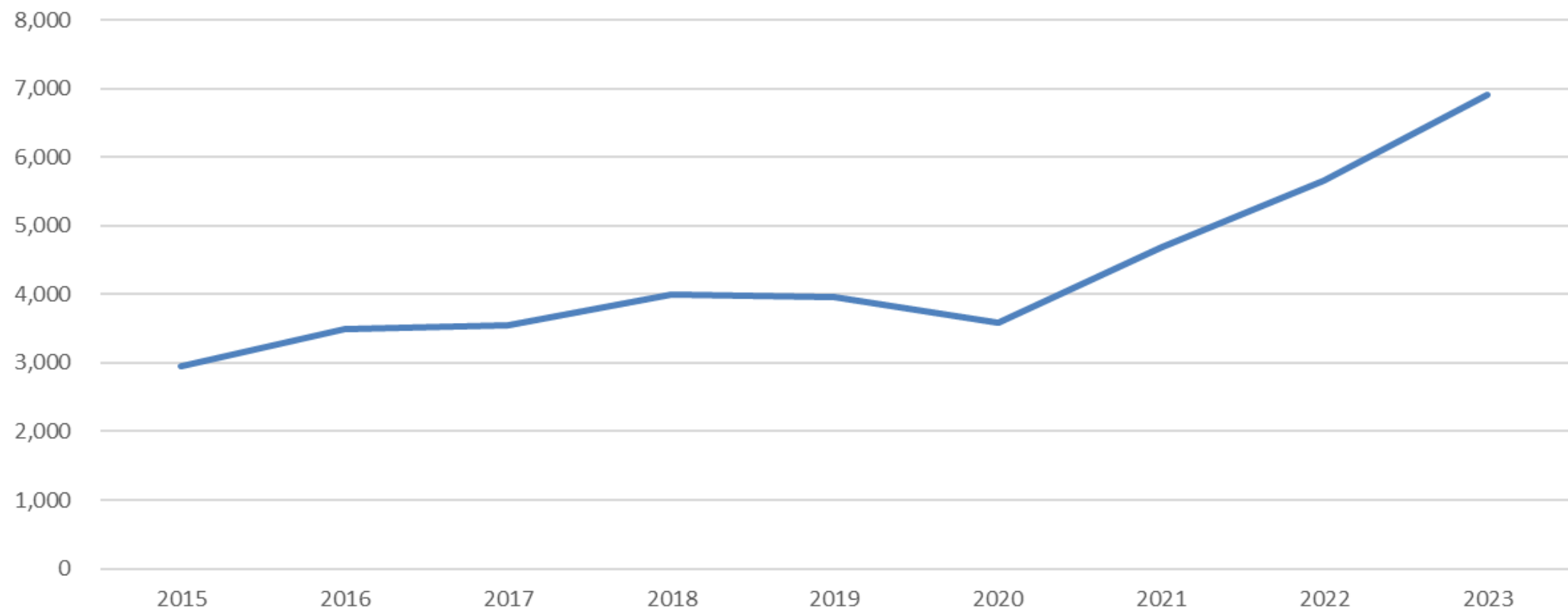
Income Statement

Units : NT \$ M	2020	2021	2022	2023	2024/Q1
Revenues	3,580	4,684	5,650	6,911	2,244
Gross Profit	1,456	1,667	2,084	2,201	610
Operating Expenses	991	1,112	1,374	1,483	404
Operating Income	465	555	710	718	206
Income Before Tax	389	524	736	860	281
Net Income	305	420	568	650	209
EPS	3.80	5.23	7.08	8.10	2.61
Gross Margin	41%	36%	37%	32%	27%
Operating Margin	13%	12%	13%	10%	9%
Income Before Tax Margin	11%	11%	13%	12%	12%

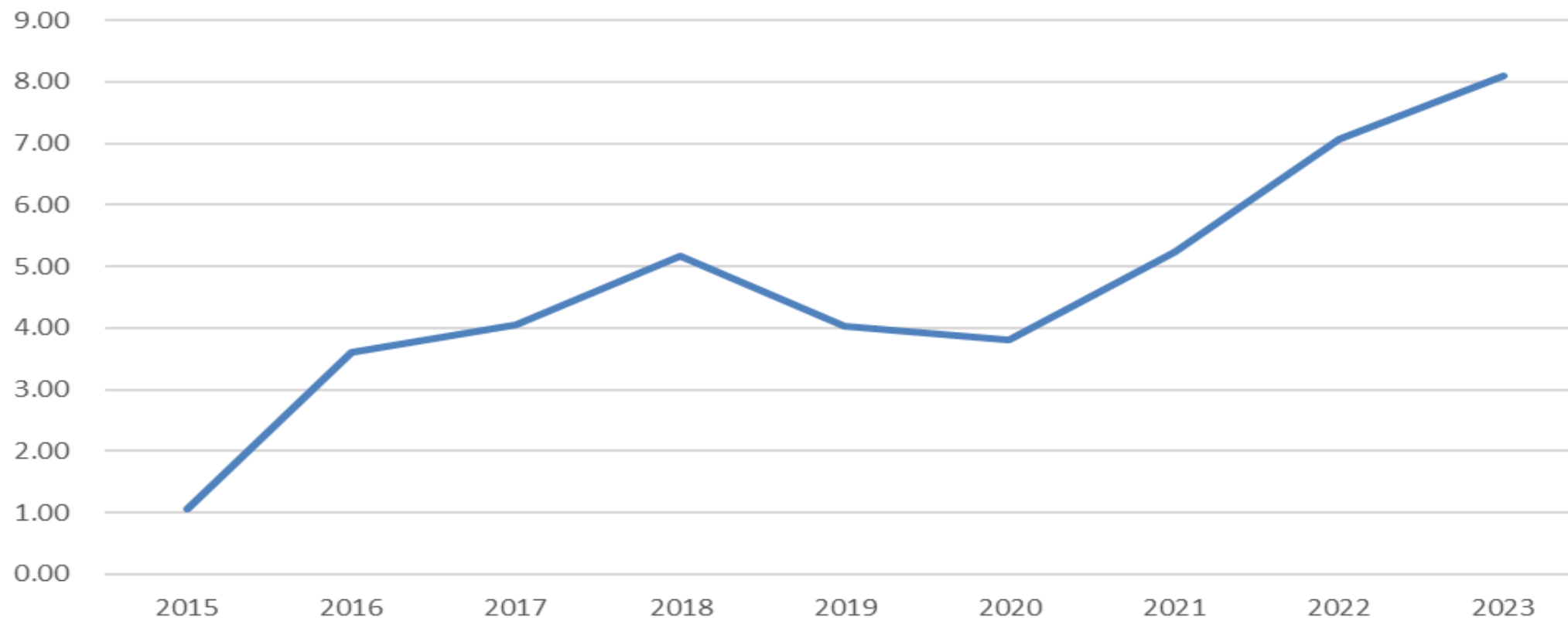
Revenue



Units NT \$ M	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024/3M
Revenue	2,942	3,495	3,539	3,988	3,949	3,580	4,684	5,650	6,911	2,244

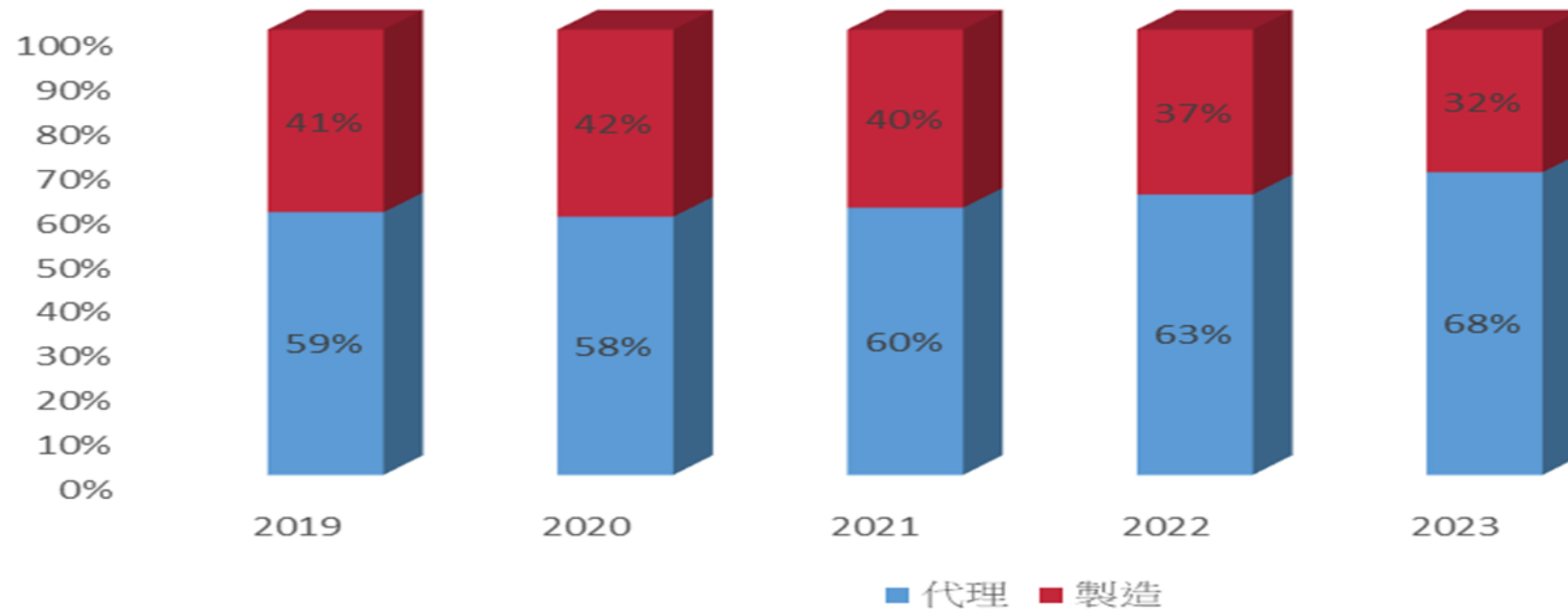


	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024/3M
EPS	1.06	3.60	4.05	5.16	4.02	3.8	5.23	7.08	8.10	2.61



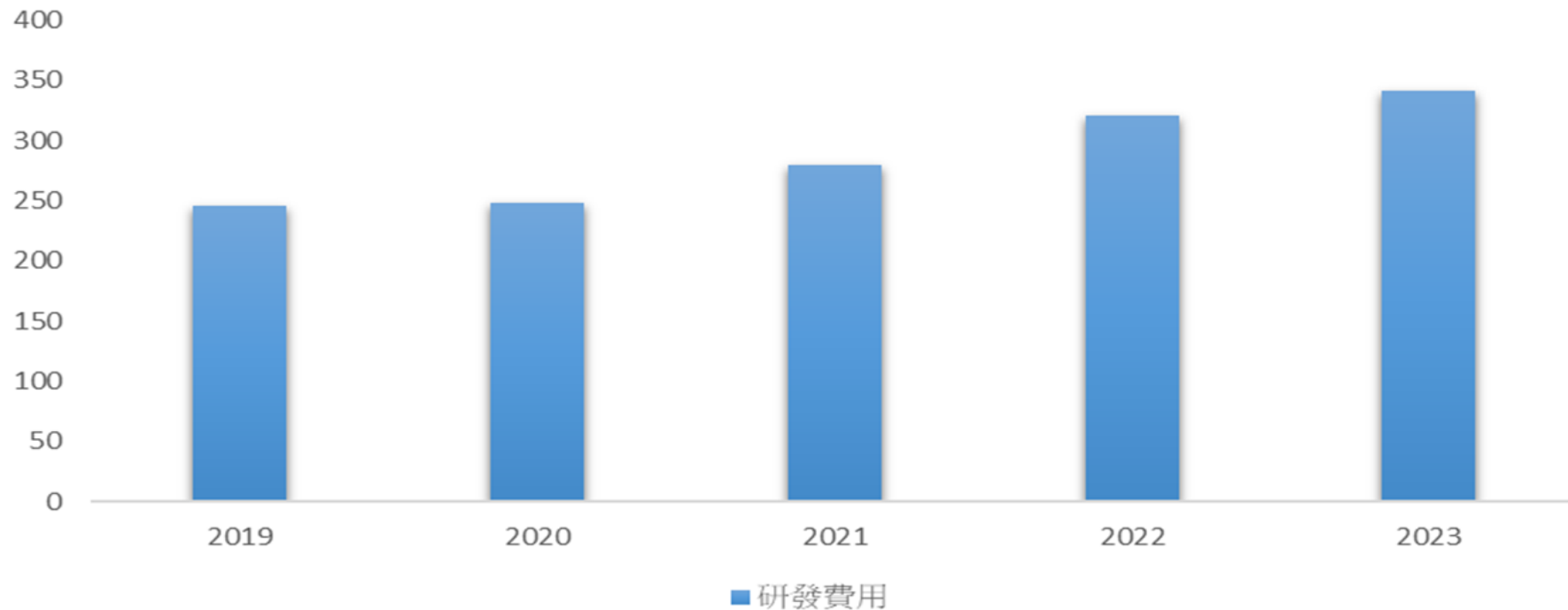
Products Mix

Units : %	2019	2020	2021	2022	2023	2024/3M	Gross Margin
Trading	59	58	60	63	68	65	Below Average
Manufacturing	41	42	40	37	32	35	Above Average



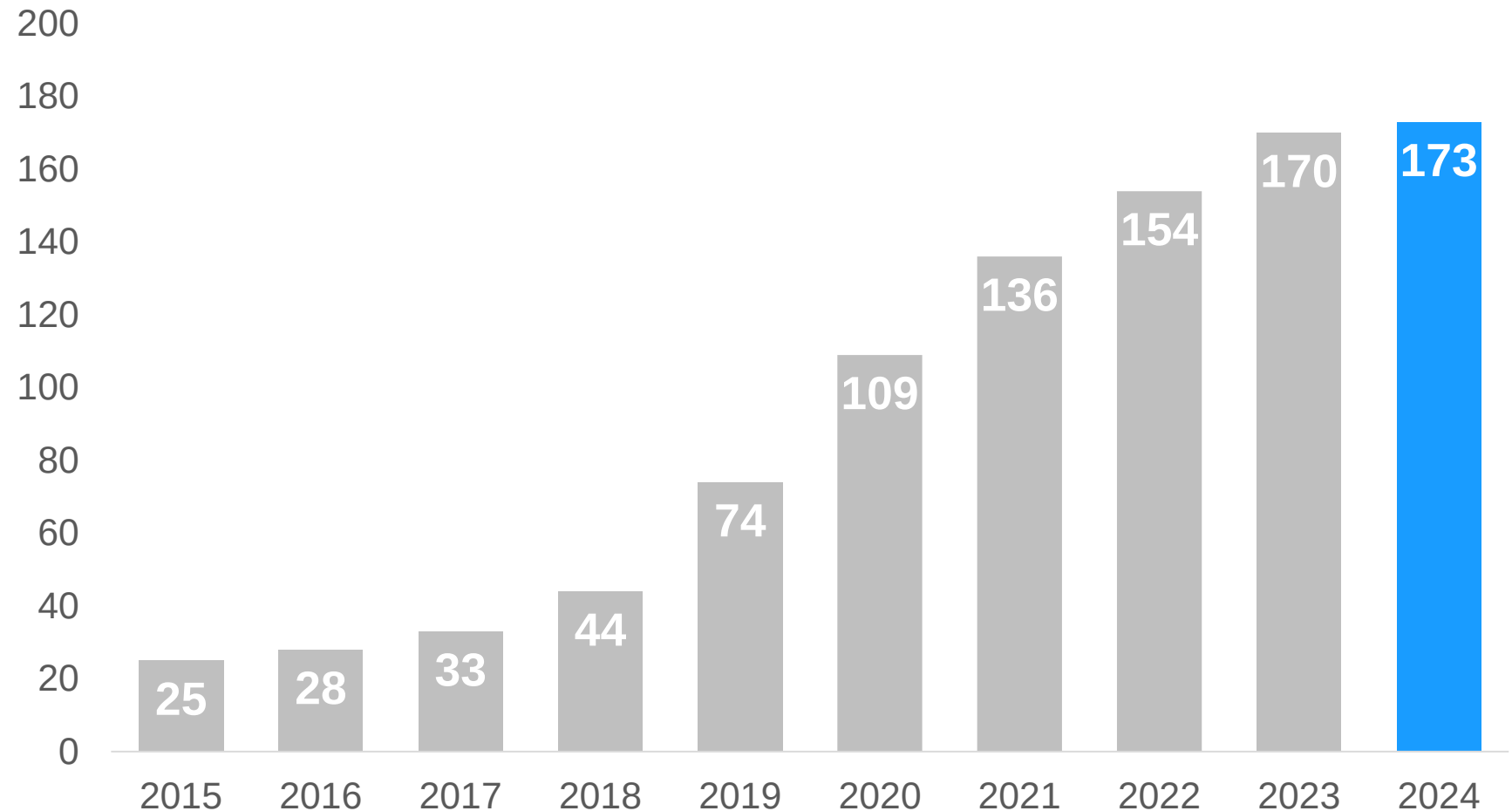
R&D Expenses

Units NT \$ M	2019	2020	2021	2022	2023	2024/3M
R&D Expenses	246	248	280	320	341	85
Expenses as % of Revenue	6.2%	6.9%	6.0%	5.7%	4.9%	3.8%
Expenses as % of Manufacturing	15.2%	16.5%	14.9%	15.3%	15.7%	11.0%



R&D Patents Number

- The cumulative number of patents on file is 173, and 51 applications are pending.

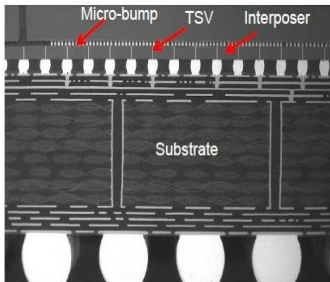
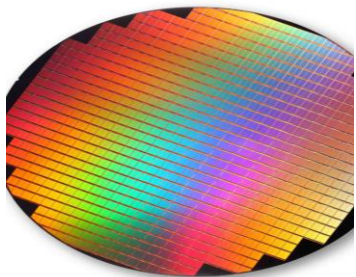


Products



What We Do

- **Industries which we serve :**
 - **Semiconductor (Front-End and Advanced Packaging)**
 - **Compound Semiconductor**
 - **LED / Mini LED / Micro LED**
 - **Flat Panel Display**
 - **Solar Cell / Battery**
 - **Biotech / Chemistry Analysis / Scientific Instrument,...**



Product and Technology

- Semiconductor
- Compound SEMI
- LED / Micro LED
- Flat Panel Display
- Solar Cell / Battery
- Biotech
- Scientific Inst.

**Equipment
Design
M'fg**

- Wet-Process Tools
- Wafer Temporary Bonding
Debonding System
- SEMI / Compound / LED

**Representative
/ Distributor**

**Wafer Reclaim
Service**

- 12" Si Wafer
- 6" SiC Wafer

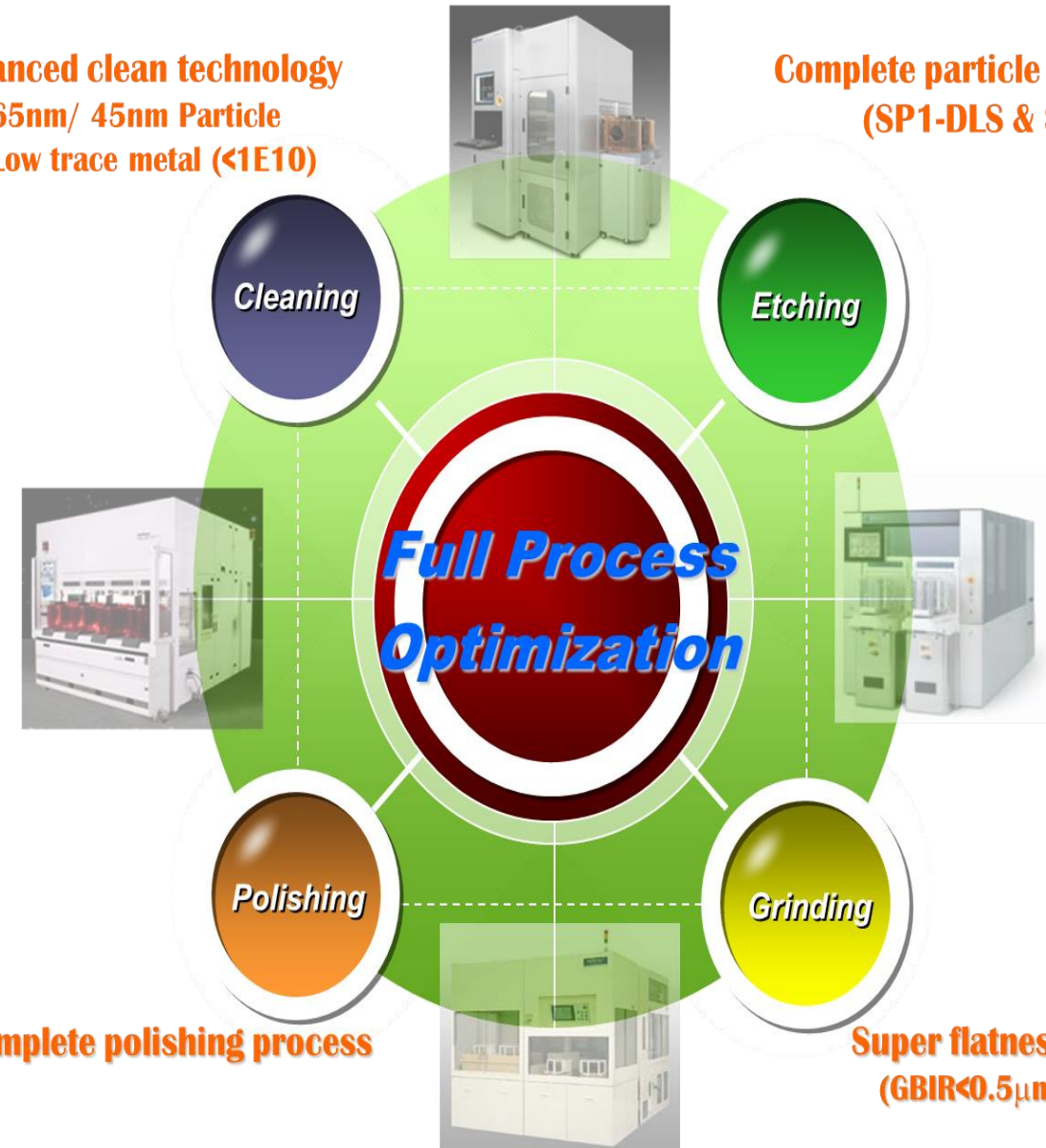
Wafer Reclaim Service

- **12" Wafer Reclaim**
 - Capacity: 160K/Month
 - Cu and Non-Cu Process
- **SiC Post Slicing Process and Reclaim**
 - Capacity: 800片/Month

Advanced clean technology

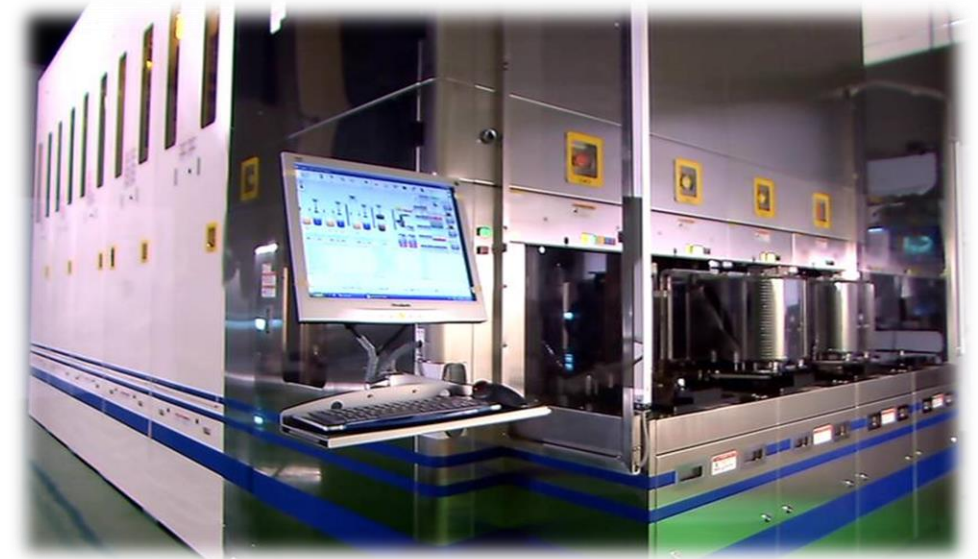
- 65nm/ 45nm Particle
- Low trace metal ($<1E10$)

Complete particle inspection
(SP1-DLS & SP2)



Wet Process Equipment

- **Wet-Bench / Single-Wafer Wet Process Equipment**
- **Applications :**
 - Advanced Packaging Process
 - Semiconductor Front-End Process
 - Compound Semiconductor
 - Microelectromechanical Systems (MEMS)
 - High-End LED Fully-Automatic Advanced Process

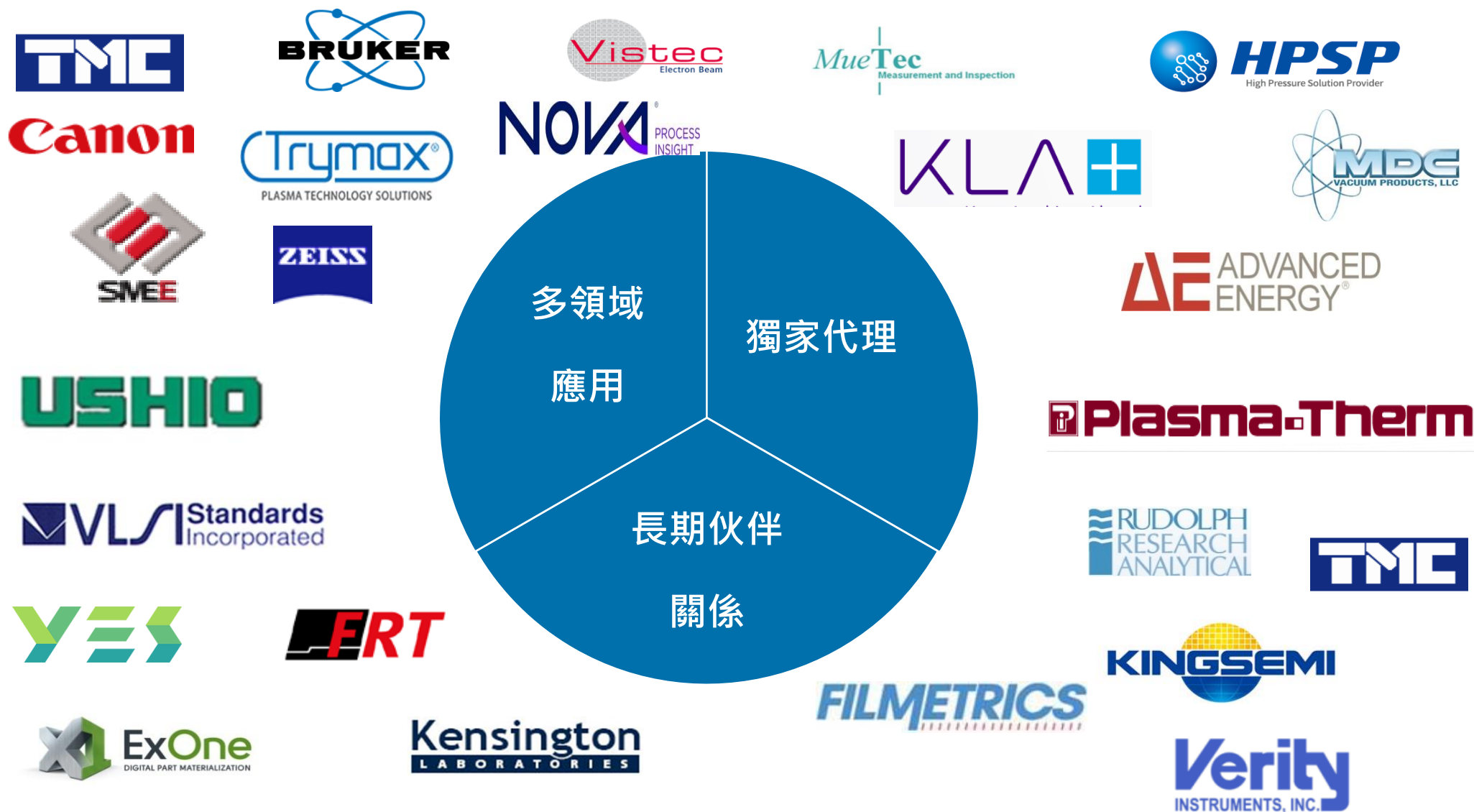


Temporary Bonding Debonding System

- **Temporary Bonding Debonding System (TBDB)**
- **Application: IGBT Power Device, Advanced Packaging for Semiconductor and LED**
 - Temporary Bonding System
 - Temporary Debonding System
 - Release Layer Formation System
 - Carrier (Glass) Recycling System



Trading(Agent/Distributor)



Corporate Governance



ISO Certifications

Initial Certification

2014/5/27

Valid Date :

2020/5/28 ~ 2023/5/27



Issue 4. Certified since

2010/3/24

Valid Date :

2019/4/30 ~ 2022/4/30



Issue 3. Certified since

2019/4/30

Valid Date :

2019/4/30 ~ 2022/4/30



Issue 1. Certified since

2019/11/20

Valid Date :

2019/11/20 ~ 2022/11/19



Issue 1. Certified since

2021/09/29

Valid Date :

2021/09/29 ~ 2024/09/28



ISO14001

ISO45001

ISO27001
資訊安全

ISO22301
營運持續

ISO9001

• TIPS-AA級驗證



Taiwan Intellectual Property Management System

台灣智慧財產管理規範 (TIPS) 驗證登錄證書

Certificate of Taiwan Intellectual Property Management System

貴公司所建置之智慧財產管理制度，通過台灣智慧財產管理規範 (TIPS) 推行體系之驗證，特此證明。相關登錄事項如下：

- 一、公司名稱：卓新企業股份有限公司
- 二、受評部門：全公司
- 三、受評地址：新竹縣港口鄉中華路16號
- 四、證書編號：TIPS-2019-驗證-008
- 五、有效期限：2021/12/31
- 六、管理標的：☒專利 ☒商標 ☐著作權 ☐營業秘密 ☐積體電路佈局
- 排除適用：無
- 七、驗證類別：☒AA級 ☐A級 (2016年版)

經濟部工業局
局長 呂正華

Certificate of Compliance

This is to certify that the Intellectual Property Management System of the following organization has been verified and fulfilled the requirements of TIPS.

- 1. Company Name : Sciencetech Corporation
- 2. Registered Department : All Company
- 3. Registered Address : No. 16, Jhonghua Rd., Hukou Township, Hsinchu County 30352, Taiwan (R.O.C.)
- 4. Number of Registration : TIPS-2019-cert-008
- 5. Date of Expiration : December 31, 2021
- 6. Items : ☒ Patent ☒ Trademark ☐ Copyright ☐ Trade Secret ☐ Integrated Circuit Layout
- Exclusion : None
- 7. Certification Level : ☒ AA ☐ A (2016)

Director General
Industrial Development Bureau, MOEA Richard Lee

Future Prospect





SCIENTECH

Thank You!

<https://www.scientech.com.tw>